



- **Preview:** SID 2010 Seattle - PolyIC exhibits from May 23rd - May 28th, 2010 May 18, 2010
- **Preview:** Gold Sponsor PolyIC to exhibit on the LOPE-C 2010 May 31st to June 2nd, 2010
- **Applications:** Foil to touch
- **Review:** HANNOVER MESSE 2010 Electronic authentication
- **Preview:** SMT/HYBRID/PACKAGING 2010 - PolyIC present with a lecture

## Dear Readers,



Certainly you have realized that in the last time you got frequently lot of information from our side. The reason for this is that we would like to let you know what you can expect from PolyIC at the next fairs and conferences.

The next upcoming conference is the SID 2010 in Seattle, USA. There we will present our transparent conductive films. More

about this you can read in our section "applications".

Only a few days later there will be the LOPE-C 2010 in Frankfurt - the annual conference and fair of the Organic Electronics Association (OE-A). In our section "preview" you can get more information about what you can expect at our booth.

Our experiences regarding the HANNOVER MESSE we will share with you in our paragraph "review".

I wish you an exciting read.

Yours sincerely  
**Wolfgang Mildner**  
 Managing Director

PolyIC is a member of:



### Preview:

**SID 2010 Seattle - PolyIC exhibits from May 23rd - May 28th, 2010**



PolyIC exhibits its transparent conductive films at the SID (International Symposium, Seminar and Exhibition) from May 23rd - May 28th, 2010 at the Washing-

ton State Convention and Trade Center Seattle. This established conference and fair is this year taking place for the 48th time in it's history.

Visit us at our **booth no. 423** or take part at the panel discussion with Mr Wolfgang Mildner, Managing Director PolyIC, on Monday 24th of May 2010 during the business conference. The topic of session VI will be: "E-Paper and Flexible Displays". This session starts at 4:35 p.m.

### Preview:

**Gold Sponsor PolyIC to exhibit on the LOPE-C 2010 May 31st to June 2nd, 2010**



This year, too, PolyIC will exhibit in **Booth B10** of the LOPE-C (Large-area Organic and Printed Electronics Convention) in the Congress Center of Messe Frankfurt am Main from May 31st to June 2nd as a

Gold Sponsor.

PolyIC's exhibition will focus on the following:

#### Transparent conductive films

The transparent, conductive films by PolyIC are perfectly suited to replace ITO films, and they are used, for example, for touch

sensors, displays, electric heating elements or for ESD/EMC protection.

## PolyID®: printed RFID

Here you see the customer terminal implemented with a big mail-order retailer as well as an anti-product piracy application. In addition, we show you the evaluation kit for printed RF tags. This will be available after the LOPE-C 2010.

## PolyLogo®: printed displays and smart objects

PolyLogo® is PolyIC's interactive optic label for marketing or trademark applications. With a "Raffle Ticket", during the OE-A demonstrator activities you can win in a raffle at the LOPE-C.

## Printed memory

Functional rewritable polymer memory, produced in cooperation with Thin Film Electronics in a high throughput roll-to-roll printing process, make possible the next generation of interactive toys and much more.

In addition, PolyIC will be present with three lectures on various subjects of printed electronics. Learn here about the individual lectures.

## Applications:

### Foil to touch



PolyIC offers transparent conductive foils which are produced in a roll-to-roll production process for applications such as displays, touch sensors or ultra-thin heating elements. They comprise a coating with maximum electric conductivity.

Prior to use, considerable effort is generally necessary to structure the conductive material, currently mostly ITO (indium tin oxide). Here a newly developed process by PolyIC presents an economic alternative with improved use features.

Special **advantages** of PolyIC's conductive foil:

- > Individual layout
- > High transparency (in the 400 nm 800 nm range)
- > Individual sheet resistance, high conductivity
- > Thin and flexible polyester substrates
- > High-throughput roll-to-roll production

## Review:

### HANNOVER MESSE 2010 Electronic authentication



At the HANNOVER MESSE, PolyIC presented the authentication application of the PolyID product line. With the Product Protection joint booth, for the first time the HANNOVER MESSE addressed the important issue of trademark and product protection as a subject of its own which has continuously been gaining importance for several years. The scope of solutions offered for

combating product piracy was very wide and ranged from optical safety features to danger potential analysis support and chemical markers.

PolyIC explained to the visitors the concept of electronic authentication with printed electronics and showed this solution on-site using a demonstrator. This electronic authentication is particularly well suited for the automatic control of bulk goods such as consumables.

If you are interested in our solution, please contact the product manager.

## Preview:

### SMT/HYBRID/PACKAGING 2010 - PolyIC present with a lecture



On Wednesday, June 9th, 2010, during the SMT/HYBRID/PACKAGING 2010 from 14:00 to 16:15 o'clock a German-language expert forum of the OE-A will take place: "Organic and printed electronics" - Production and Applications in Hall 6, Messezentrum Nuremberg.

Dr. Wolfgang Clemens, Head of Applications at

PolyIC, will there give a lecture on the subject of "**Applications of printed electronics on the way to the market**" and afterwards be available for discussion.

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